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Listing of Claims:

Claim 1 (original): A scribe line structure, comprising:

a substrate;

a plurality of dielectric layers formed on the surface of the substrate comprising at least a process monitor pattern set in a scribe line region; and

a dummy metal structure formed on the surface of the substrate connecting with the process monitor pattern and exposed in the scribe line region.

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Claim 2 (original): The scribe line structure of claim 1 wherein the plurality of dielectric layers comprise dielectric layers having a dielectric constant less than or equal to 3.

15 Claim 3 (original): The scribe line structure of claim 1 wherein the dummy metal structure comprises a plurality of dummy vias.

Claim 4 (original): The scribe line structure of claim 1 wherein the dummy metal structure comprises a plurality of dummy metal layers.

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Claim 5 (original): The scribe line structure of claim 1 wherein the process monitor pattern is made of metal materials.

Claim 6 (original): The scribe line structure of claim 1 wherein the process monitor pattern comprises test keys, feature dimension measuring elements, or alignment marks.

Claim 7 (original): The scribe line structure of claim 1 wherein the surface

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of the substrate further comprises a protective layer covering two sides of the surface of dielectric within the scribe line region.

Claim 8 (original): A scribe line structure, comprising:

a substrate, the surface of the substrate comprising at least a scribe line region;

a plurality of dielectric layers formed on the surface of the substrate comprising at least a process monitor pattern set in the scribe line region; and

a heat irradiative structure formed in the plurality of dielectric layers connecting the plurality of dielectric layers with the surface of the substrate and exposed in the scribe line region.

Claim 9 (original): The scribe line structure of claim 8 wherein the plurality of dielectric layers comprise dielectric layers having a dielectric constant less than or equal to 3.

Claim 10 (original): The scribe line structure of claim 8 wherein the heat irradiative structure is a dummy metal structure.

Claim 11 (original): The scribe line structure of claim 10 wherein the dummy metal structure comprises a plurality of dummy vias.

Claim 12 (original): The scribe line structure of claim 10 wherein the dummy metal structure comprises a plurality of dummy metal layers.

Claim 13 (original): The scribe line structure of claim 8 wherein the heat irradiative structure connects with the process monitor pattern.

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Claim 14 (original): The scribe line structure of claim 8 wherein the process monitor pattern is made of metal materials.

Claim 15 (original): The scribe line structure of claim 8 wherein the process monitor pattern comprises test keys, feature dimension measuring elements, or alignment marks.

Claim 16 (previously presented): The scribe line structure of claim 8 wherein the surface of the substrate further comprises a protective layer covering two sides of the surface of dielectric within the scribe line region.